SCAS538D - OCTOBER 1995 - REVISED OCTOBER 2002

- 4.5-V to 5.5-V V_{CC} Operation
- Inputs Accept Voltages to 5.5 V
- Max t_{pd} of 9.5 ns at 5 V
- Inputs Are TTL-Voltage Compatible

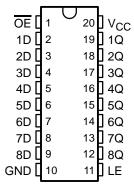
description/ordering information

These 8-bit latches feature 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. The devices are particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

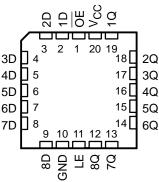
The eight latches are D-type transparent latches. When the latch-enable (LE) input is high, the Q outputs follow the data (D) inputs. When LE is taken low, the Q outputs are latched at the logic levels set up at the D inputs.

A buffered output-enable (\overline{OE}) input can be used to place the eight outputs in either a normal logic state (high or low logic levels) or the high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines in a bus-organized system without need for interface or pullup components.

SN54ACT573 . . . J OR W PACKAGE SN74ACT573 . . . DB, DW, N, NS, OR PW PACKAGE (TOP VIEW)



SN54ACT573 . . . FK PACKAGE (TOP VIEW)



OE does not affect the internal operations of the latches. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

ORDERING INFORMATION

TA	PACKAGE [†]		ORDERABLE PART NUMBER	TOP-SIDE MARKING	
	PDIP – N	Tube	SN74ACT573N	SN74ACT573N	
	SOIC - DW	Tube	SN74ACT573DW	ACT573	
-40°C to 85°C	30IC - DW	Tape and reel	SN74ACT573DWR		
-40 C to 65 C	SOP - NS	Tape and reel	SN74ACT573NSR	ACT573	
	SSOP – DB Tape and reel		SN74ACT573DBR	AD573	
	TSSOP – PW Tape and r		SN74ACT573PWR	AD573	
	CDIP – J	Tube	SNJ54ACT573J	SNJ54ACT573J	
–55°C to 125°C	CFP – W	Tube	SNJ54ACT573W	SNJ54ACT573W	
	LCCC – FK	Tube	SNJ54ACT573FK	SNJ54ACT573FK	

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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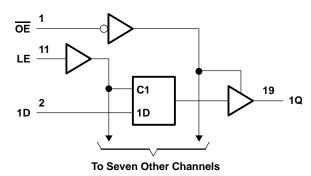


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FUNCTION TABLE (each latch)

	OUTPUT		
ŌĒ	LE	D	Q
L	Н	Н	Н
L	Н	L	L
L	L	Χ	Q_0
Н	X	Χ	Z

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}		–0.5 V to 7 V
Input voltage range, V _I (see Note 1)		0.5 V to V _{CC} + 0.5 V
Output voltage range, VO (see Note 1)		-0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$)		±20 mA
Output clamp current, IOK (VO < 0 or VO > VCO	c)	±20 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	- 	±50 mA
Continuous current through, V _{CC} or GND		±200 mA
Package thermal impedance, θ _{JA} (see Note 2):	: DB package	70°C/W
	DW package	58°C/W
	N package	69°C/W
	NS package	60°C/W
	PW package	83°C/W
Storage temperature range, T _{stq}		–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
 - 2. The package thermal impedance is calculated in accordance with JESD 51-7.



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recommended operating conditions (see Note 3)

		SN54ACT573		SN74A	CT573	UNIT
		MIN	MAX	MIN	MAX	UNII
Vcc	Supply voltage	4.5	5.5	4.5	5.5	V
VIH	High-level input voltage	2		2		V
VIL	Low-level input voltage		0.8		0.8	V
٧ _I	Input voltage	0	VCC	0	VCC	V
٧o	Output voltage	0	Vcc	0	Vcc	V
ІОН	High-level output current		-24		-24	mA
lOL	Low-level output current		24		24	mA
Δt/Δν	Input transition rise or fall rate		8		8	ns/V
TA	Operating free-air temperature	-55	125	-40	85	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETED	TEST COMPLTIONS	V	T _A = 25°C			SN54A	CT573	SN74ACT573		UNIT
PARAMETER	TEST CONDITIONS	VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNII
	Jan - 50 uA	4.5 V	4.4	4.49		4.4		4.4		
	I _{OH} = -50 μA	5.5 V	5.4	5.49		5.4		5.4		
	Jan - 24 mA	4.5 V	3.86			3.7		3.76		V
VOH	$I_{OH} = -24 \text{ mA}$	5.5 V	4.86			4.7		4.76		V
	$I_{OH} = -50 \text{ mA}^{\dagger}$	5.5 V				3.85				
	I _{OH} = -75 mA†	5.5 V						3.85		
	In. 50A	4.5 V			0.1		0.1		0.1	V
	I _{OL} = 50 μA	5.5 V			0.1		0.1		0.1	
.,	In 24 mA	4.5 V			0.36		0.44		0.44	
VOL	I _{OL} = 24 mA	5.5 V			0.36		0.44		0.44	
	I _{OL} = 50 mA [†]	5.5 V					1.65			
	I _{OL} = 75 mA [†]	5.5 V							1.65	
loz	V _O = V _{CC} or GND	5.5 V			±0.25		±5		±2.5	μА
l _l	V _I = V _{CC} or GND	5.5 V			±0.1		±1		±1	μΑ
ICC	$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V			4		80		40	μΑ
Δl _{CC} ‡	One input at 3.4 V, Other inputs at GND or V _{CC}	5.5 V		0.6			1.5		1.5	mA
Ci	V _I = V _{CC} or GND	5 V		5						pF

[†] Not more than one output should be tested at a time, and the duration of the test should not exceed 2 ms.

timing requirements over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

		T _A = 25°C		SN54ACT573		SN74ACT573		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	UNIT
t _W	Pulse duration, LE high	3.5		5		4		ns
t _{su}	Setup time, data before LE↓	3		4.5		3.5		ns
th	Hold time, data after LE↓	0		1		0		ns



[‡] This is the increase in supply current for each input that is at one of the specified TTL voltage levels, rather than 0 V or V_{CC}.

SN54ACT573, **SN74ACT573 OCTAL D-TYPE TRANSPARENT LATCHES** WITH 3-STATE OUTPUTS SCAS538D - OCTOBER 1995 - REVISED OCTOBER 2002

switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

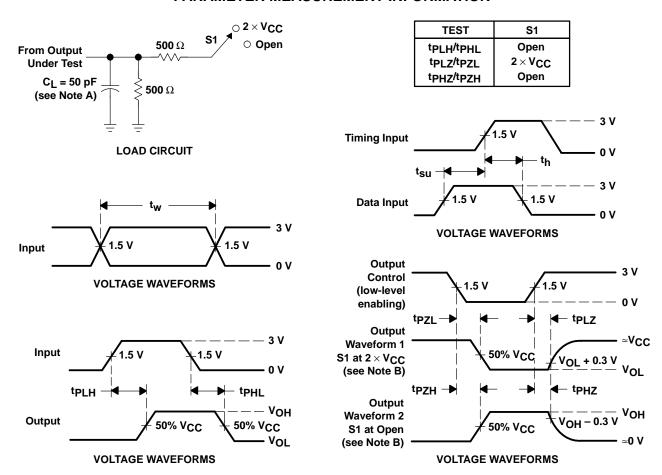
PARAMETER	FROM	то	T,	4 = 25°C	;	SN54A	CT573	SN74A	CT573	UNIT
PARAMETER	(INPUT)	(OUTPUT)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
^t PLH	D	Q	2.5	6	10.5	1.5	13.5	2	12	20
^t PHL	Б	y	2.5	6	10.5	1.5	13.5	2	12	ns
^t PLH	LE	Q	3	6	10.5	1.5	13	2.5	12	20
^t PHL	LE	y	2.5	5.5	9.5	1.5	12	2	10.5	ns
^t PZH	05	Q	2	5.5	10	1.5	11.5	1.5	11	20
^t PZL	OE	y	1.5	5.5	9.5	1.5	11	1.5	10.5	ns
^t PHZ	ŌĒ	Q	2.5	6.5	11	1.5	13.5	1.5	12.5	ns
t _{PLZ}	OE .	1.		5	8.5	1.5	10.5	1	9.5	115

operating characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$

	PARAMETER	TEST CO	TYP	UNIT	
C _{pd}	Power dissipation capacitance	C _L = 50 pF,	f = 1 MHz	25	pF



PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_Q = 50 \ \Omega$, $t_f \leq 2.5 \ ns$, $t_f \leq 2.5 \ ns$.
- D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms





v.ti.com 8-Jun-2005

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
5962-87664012A	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
5962-8766401RA	ACTIVE	CDIP	J	20	1	TBD	Call TI	Level-NC-NC-NC
5962-8766401SA	ACTIVE	CFP	W	20		TBD	Call TI	Level-NC-NC-NC
SN74ACT573DBLE	OBSOLETE	SSOP	DB	20		TBD	Call TI	Call TI
SN74ACT573DBR	ACTIVE	SSOP	DB	20	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74ACT573DBRE4	ACTIVE	SSOP	DB	20	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74ACT573DW	ACTIVE	SOIC	DW	20	25	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR/ Level-1-235C-UNLIM
SN74ACT573DWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ACT573DWR	ACTIVE	SOIC	DW	20	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR/ Level-1-235C-UNLIM
SN74ACT573DWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ACT573N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74ACT573NE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74ACT573NSR	ACTIVE	SO	NS	20	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74ACT573NSRE4	ACTIVE	SO	NS	20	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74ACT573PW	ACTIVE	TSSOP	PW	20	70	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
SN74ACT573PWE4	ACTIVE	TSSOP	PW	20	70	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
SN74ACT573PWLE	OBSOLETE	TSSOP	PW	20		TBD	Call TI	Call TI
SN74ACT573PWR	ACTIVE	TSSOP	PW	20	2000	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
SN74ACT573PWRE4	ACTIVE	TSSOP	PW	20	2000	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
SNJ54ACT573FK	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
SNJ54ACT573J	ACTIVE	CDIP	J	20	1	TBD	Call TI	Level-NC-NC-NC

 $^{^{(1)}}$ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.



PACKAGE OPTION ADDENDUM

8-Jun-2005

retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F20)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within Mil-Std 1835 GDFP2-F20



FK (S-CQCC-N**)

28 TERMINAL SHOWN

LEADLESS CERAMIC CHIP CARRIER



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. The terminals are gold plated.
- E. Falls within JEDEC MS-004



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



DW (R-PDSO-G20)

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AC.



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-150

PW (R-PDSO-G**)

14 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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